

**Apparatus and Method for Depositing and Planarizing Thin Films of
Semiconductor Wafers**

ABSTRACT OF THE DISCLOSURE

5 An electroplating apparatus for depositing a metallic layer on a surface of a wafer
is provided. In one example, a proximity head capable of being electrically charged as an
anode is placed in close proximity to the surface of the wafer. A plating fluid is provided
between the wafer and the proximity head to create localized metallic plating.

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